



Bruce M Misner
DBA Advanced Technical Services

Biographical Sketch

Bruce Misner is the principal of Advanced Technical Services, serving the electronics industry with manufacturing engineering consulting services related to:

- Electronic based Product, Process and Facility Development
- Microelectronics Packaging and Electronics Miniaturization utilizing SMT, Thick and Thin Film Hybrid, Multi-Chip Module (MCM), Chip-on-Board, Microwave Integrated Circuit (MIC), Wire Bond and Flip Chip technologies
- Complete Failure Analysis with follow up Design, Material and Manufacturing Process Corrective Actions
- Tin Whisker and Counterfeit Mitigation
- High Reliability Automotive, Military, Space and Medical Applications



Mr. Misner has served as the VP of Technology Development for Engent, in Atlanta, GA after completing a 17 year career with Orbital ATK as their multi-site Subject Matter Expert in electronics manufacturing technology. This included electronics technical lead on the billion dollar AARGM missile program. He concurrently served as the Technical Director of the Orbital ATK Failure Analysis Lab based in Clearwater, FL and played a role in the successful launch of the LADEE moon mission in 2013.

Prior to ATK, Mr. Misner' career spanned various roles in electronic and microelectronic engineering. This included the head of Electromagnetic Sciences microelectronics development and production operations (now part of Honeywell) and the VP of Operations for Hy Tec Industries. He started his career as a process development engineer for, at the time, the nation's largest independent producer of custom hybrid circuits, Circuit Technology, Farmingdale, NY, now part of Cobham Aeroflex Corporation.

Mr. Misner has a Bachelor of Science degree from Binghamton University and was a candidate for an MBA at Cornell University. He has been an active member for multiple decades and often chapter officer in SMTA and ISHM/IMAPS, as well as affiliation with JEDEC JC13.5 as a Task Group Chairman for Space Class Hybrid Device requirements. His latest technical paper, "Validated Solder Coverage for Tin Whisker Mitigation," was published in the Journal of Surface Mount Technology, July – Sept 2016, Volume 29, Issue 3 and can be viewed here:

http://smta.org/knowledge/journal_detail.cfm?ARTICLE_ID=253